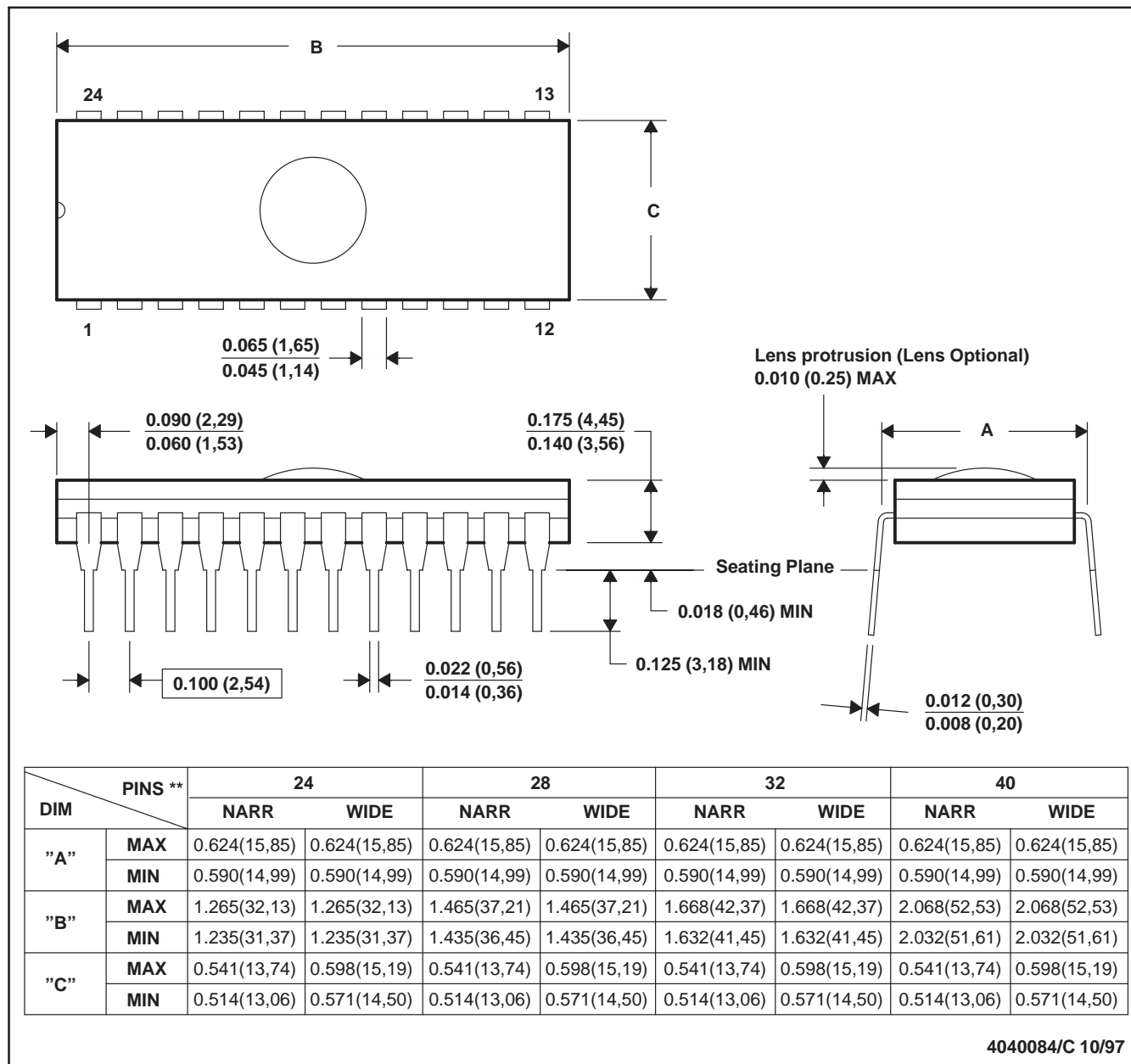


J (R-CDIP-T)****CERAMIC DUAL-IN-LINE PACKAGE**

24 PIN SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Window (lens) added to this group of packages (24,28,32,40 pin).
 D. This package can be hermetically sealed with a ceramic lid using glass frit.
 E. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.

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